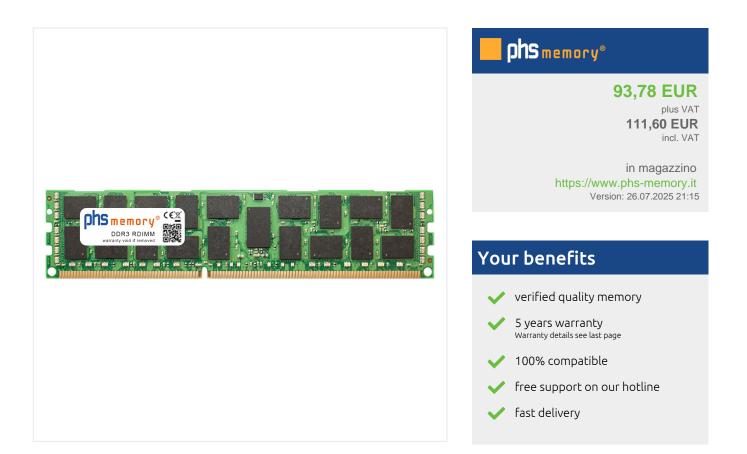


32GB Computer memory DDR3 for ORACLE SUN Fire X2270 RDIMM



PHS-memory® - computer memory with 100% quality

- many years of IT competence
- Free support for optimal configuration and product selection
- High availability through professional warehouse management
- Fast delivery in throughout Europe
- Short response times and professional order processing due to full digitalization throughout the entire process with complete traceability
- Incoming goods inspection include checks of the DRAMs, PCBs and the programmed SPDs in order to exclude possible errors (Controlled BOM).
- PHS-memory® brand memories guarantee 100% compatibility to the specified system.
- PHS-memory® memories can be used together with existing memories in the device depends on to the configuration rules of the system.
- The "fallback option" in the SPD of PHS-memory® allows DRAMs with higher clock rates to be operated together with older memory modules with lower clock rates within the system.
- Products with unique serial number for service and warranty
- Pre-sales and after-sales support by technically trained personnel



Memory Specification



| Memory size | 32GB | | |
|---------------------------|------------------------|--|--|
| Memory technology | DDR3 | | |
| ECC support | yes | | |
| JEDEC Norm | PC3-10600R | | |
| DRAM Organization | 2Gx4 | | |
| Rank | 4Rx4 (4DRx4 DDP) | | |
| Туре | RDIMM (ECC Registered) | | |
| Number of pins | 240 Pin DIMM | | |
| Memory data transfer rate | 1333MHz @ CL9 | | |
| Speciality | DDP | | |
| Board dimensions | 133,35 x 30 (LxB mm) | | |
| Operating temperature | 0° C - 85° C | | |
| Storage temperature | -40° C - +95° C | | |
| RoHS compliant | yes | | |
| SKU | SP466102 | | |
| EAN | 4067488296154 | | |

overRAMing maximize your RAM



Most systems - including the ORACLE SUN Fire X2270 - can be upgraded with more memory than originally specified by the device manufacturer.

Therefore, our memory specialists continuously analyze new memory solutions in selected systems. Due to improved manufacturing technologies, new memories with higher performance and capacity will be tested for stability and functionality. Then the new memory solutions are released for the respective systems.

released for the respective systems. Use the benefits of larger computer memory capacity with the PHSmemory® overRAMing memory solutions.

https://www.phs-memory.it/-BOR

Note: The module specified in this datasheet is one of several possible configurations available under this part number.

Some details may differ from the specifications described here and the illustration, but have no negative influence on the functionality.



System Specifications

The memory is 100% compatible with this sytem:

| System manufacturer | ORACLE |
|--------------------------|---|
| Device type | Server |
| Device family | SUN Server |
| Device series | Fire X Serie |
| Device name | SUN Fire X2270 |
| Maximum memory* | 384GB / 192GB according to manufacturer |
| Number of memory sockets | 12 |

* The specifications for the maximum memory upgrade may differ from those of the manufacturer ORACLE. Often the information given in the manual for the maximum memory upgrade is not up to date. New memory technologies, bios updates or newer software versions often allow the use of memory modules with a higher capacity than specified by the manufacturer with the same performance and stability.

Memory modules with our overRAMing-symbol are approved by us for maximum memory expansion.

Information on memory allocation

Computer memory configuration:

Our memory team will be happy to help you choose the right memory and configure your server.

| Technologie | GB /Modul | Anzahl | Total |
|-------------|-----------|--------|-------|
| RDIMM | 16GB RAM | 12 | 192GB |

Principles of memory assembly

• Es können nur die memorysteckplätze genutzt werden, bei denen die jeweilige CPU vorhanden ist.

Memory configuration for good system performance

• Wenn mehr als eine CPU vorhanden sind, sollten die memory pro CPU identisch (gespiegelt zur anderen CPU) bestückt werden.

Information on memory installation

- Turn off the system
- Remove the plug of the power supply unit (if connected)
- Remove the battery, according to the user manual of the system
- Always ground yourself before touching electronic components
- Protect the memory module from static voltages:
 - Do not touch the gold pins of the memory module
 - Only touch the sides of the memory module
 - Use a grounding strap and/or ESD glove if possible

General installation instructions are supplied by E-Mail.

phs memory®

Further memory options for ORACLE SUN Fire X2270

| Size | SKU | Technology | Туре | Number of pins | Brand | Reference no. |
|------|----------|------------|---------------------------|----------------|-------------|---------------|
| 8GB | SP237669 | DDR3 | RDIMM (ECC Registered) | 240 Pin DIMM | PHS-memory® | |
| 16GB | SP237667 | DDR3 | RDIMM (ECC Registered) | 240 Pin DIMM | PHS-memory® | |
| 32GB | SP466102 | DDR3 | RDIMM (ECC Registered) | 240 Pin DIMM | PHS-memory® | |

PHS-memory® warranty

Every PHS-memory® is equipped with a 5-years-warranty of perfect operation. If the RAM module is defective or fails within 5 years of purchase when used properly, you will receive an appropriate RAM module free of charge. If a suitable memory module is no longer available, we will refund the purchase price.

For more information on warranty and service please visit https://www.phs-memory.it/-W5Y



Contact Information

PHS-electronic gmbh - www.phs-memory.it -Karl-Götz-Str. 5 97424 Schweinfurt Germania Phone: +49 9721 784678 E-Mail: info@phs-memory.it Web: www.phs-memory.it

All information without guarantee. Technical changes and errors excepted. You can find current price information in our online shop at https://www.phs-memory.it